

WHAT IS CLAIMED IS:

1. A cleaning mechanism for an image sensor package, the cleaning mechanism being cleaning the substrate and the frame layer arranged on the substrate of the image sensor to form a chamber between the frame layer and the
5 substrate, the mechanism comprising:

a seal up body being formed with a cleaning room;

a rotating device located within the cleaning room of the seal up body , the substrate formed with frame layer being fixed on the rotating device, then, the chamber of the substrate being faced the centrifugal force direction from the
10 rotating device.

a cleaning device being mounted on the side of the cleaning room of the seal up body for cleaning the chamber of the substrate by cleaner.

2. The cleaning mechanism according to claim 1, wherein seal up body includes a lower element, a periphery wall, and a upper cover.

15 3. The cleaning mechanism according to claim 2, wherein the rotating device is located at the lower element of the seal up body.

4. The cleaning mechanism according to claim 2, wherein the cleaning device is mounted on the periphery wall of the seal up body.

5. The cleaning mechanism according to claim 2, wherein the cleaner of the
20 cleaning device is N2 or CO2.